

SE Series



Agency Approvals

AGENCY	AGENCY FILE NUMBER
	E128662

2 Electrode GDT Graphical Symbol



Additional Information



Datasheet



Resources



Samples

Description

Littelfuse SE series GDT offers high surge ratings in a miniature package. It's designed for surface mounting on PCB with small size 3.2x1.6x1.6mm. Low insertion loss is perfectly suited to broadband equipment applications. The capacitance does not vary with voltage, and will not cause operational problems with ADSL2+, where capacitance variation across Tip and Ring is undesirable. These devices are extremely robust and are able to divert a 500A-600A pulse in a miniature package 1206 without destruction.

Features

- RoHS compliant and Lead-free
- GHz working frequency
- Excellent stability on multiple pulse duty cycle
- Excellent response to fast rising transients.
- Ultra Low Insertion Loss
- 0.5-0.6KA surge capability tested with 8/20μS pulse as defined by IEC 61000-4-5
- Ultra small devices offered in a variety of mounting lead forms
- Non-Radioactive
- Low capacitance (<0.5pF)
- Voltage Ranges 140V to 500V
- UL recognized
- Conforms to ITU-T K12, IEC 1000-4-5
- Square Outline

Applications

- Communication equipment
- CATV equipment
- Test equipment
- Data lines
- Power supplies
- Telecom SLIC protection
- Broadband equipment
- ADSL equipment, including ADSL2+
- XDSL equipment
- Satellite and CATV equipment
- General telecom equipment

Part Number	Device Specifications (at 25°C)										Life Ratings	
	DC Breakdown in Volts (@100V/s)			Impulse Breakdown in Volts (@100V/μs)	Impulse Breakdown In Volts (@1 Kv/μsec)	Insulation Resistance	Capacitance (@1MHz)	Arc Voltage (@1A)	Glow to Arc Transition Current	Glow Voltage	Nominal Impulse Discharge Current (x10 @8/20μs)	Nominal Impulse Discharge Current (x10 @5/320μs)
	MIN	TY	MAX	MAX		MIN	MAX					
SE140	98	140	182	800	900	>1GΩ (at 100VDC)	<0.5 pf	~10 V	<1.0 A	~60 V	0.5 kA	150 A
SE200	140	200	260	700	1100		<0.3 pf		<1.0 A			
SE230	172	230	276	600	800		<0.5 pf		<1.0 A			
SE350	265	350	495	900	1150		<0.5 pf		<1.0 A			
SE470	329	470	611	1050	1200		<0.3 pf		<1.0 A		0.5 kA	
SE500	400	500	600	1050	1200		<0.3 pf		<1.0 A		0.5 kA	

Materials	Device Tin Plated 17.5±12.5 Microns Construction Ceramic Insulator.
Storage and Operational Temperature	-40 to +90 °C

The graph shows the voltage response of a Schmitt trigger over time. The y-axis is Voltage (V) and the x-axis is Time (ns). The curve starts at (0,0), rises to a peak labeled 'Max dynamic breakover voltage' at approximately 500 ns, then falls to a level labeled 'Hold-over voltage' at approximately 600 ns. The curve then remains at this level until approximately 1000 ns, where it drops to a level labeled 'On-State voltage'.

Tape Specifications

IEC 60286-3
Dimensions in mm

The drawing includes the following dimensions and features:

- Top View:** Shows a series of pockets with a center-to-center distance of 4 ± 0.1 mm. The width of the tape is 12 ± 0.3 mm. The width of the carrier is 19.9 ± 0.1 mm. The width of the individual pocket is 1.5 ± 0.05 mm. The distance from the edge of the carrier to the center of the first pocket is 1.75 ± 0.1 mm. The distance from the edge of the carrier to the center of the last pocket is 5.5 ± 0.1 mm. The diameter of the mounting holes is $\varnothing 1.1 \pm 0.1$ mm. The distance between the mounting holes is 4 ± 0.1 mm.
- Side View (A-A):** Shows the profile of the tape with a height of 3.7 ± 0.1 mm and a lead-in angle of 5° .
- Cross-section (B-B):** Shows the tape being inserted into a pocket with a depth of 2.1 ± 0.1 mm and a lead-in angle of 5° .

SMD-Tape has to withstand a minimum Force of $F > 20 \text{ N / pocket}$
2 Kg / pocket
minimum vertical load (minimum checking quantity: 10 pockets)

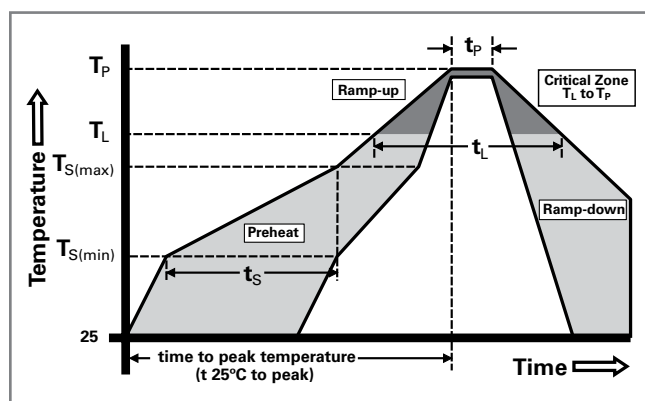
Specifications

286-3
Dimensions in mm

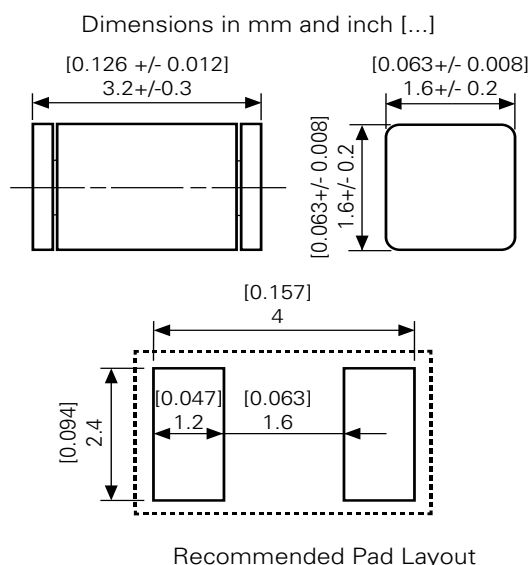
Technical drawing of the 286-3 component. The front view (left) shows a circular base with a central vertical feature. Dimensions include a total height of 20.2 min., a central feature height of 1.5 min., a base diameter of 12.8 min., a fillet radius of R0.75, and a base width of 18.4 max. The side view (right) shows a rectangular profile with a total height of 11.9 min., a base width of 12.4 +2/-0, and a maximum length of 100 min. (Ø100 min. / Ø330 max.).

Soldering Parameters - Reflow Soldering (Surface Mount Devices)

Reflow Condition		Pb – Free assembly
Pre Heat	- Temperature Min ($T_{s(min)}$)	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (Min to Max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak		3°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		5°C/second max
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		10 – 30 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes Max.
Do not exceed		260°C



Device Dimensions



Part Numbering System and Ordering Information

SE xxx

Series ———

1206 Square GDT

Breakdown Voltage ———

140 = 140V
200 = 200V
230 = 230V
350 = 350V
470 = 470V
500 = 500V

Packaging

Part Number	Packaging Option	Quantity
SE140	Tape and Reel	3,000
SE200	Tape and Reel	3,000
SE230	Tape and Reel	3,000
SE350	Tape and Reel	3,000
SE470	Tape and Reel	3,000
SE500	Tape and Reel	3,000

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Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru

moschip.ru_4

moschip.ru_6

moschip.ru_9